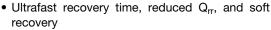


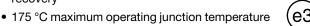
# Ultrafast Rectifier, 2 x 15 A FRED Pt®



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	2 x 15 A			
$V_{R}$	600 V			
V <sub>F</sub> at I <sub>F</sub>	0.9 V			
t <sub>rr</sub>	55 ns			
T <sub>J</sub> max.	175 °C			
Package	SMPD (TO-263AC)			
Circuit configuration	Dual serial			

#### **FEATURES**

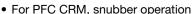




RoHS

COMPLIANT HALOGEN

FREE



Low forward voltage drop

· Low leakage current

 Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Meets JESD 201 class 2 whisker test

 Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

#### **DESCRIPTION / APPLICATIONS**

State of the art ultrafast recovery rectifiers designed with optimized performance of forward voltage drop and ultrafast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in PFC, boost, lighting, in the AC/DC section of SMPS, freewheeling and clamp diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage		$V_{RRM}$		600	V
Average rectified forward current	per device	I <sub>F(AV)</sub>	T <sub>solder pad</sub> = 143 °C	30	
	per diode			15	۸
Non vonetitive neels overe overent	per device	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C, 6 ms square pulse	300	Α
Non-repetitive peak surge current	per diode			160	

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	I <sub>R</sub> = 100 μA	600	-	-		
Converd voltage new diede	V	I <sub>F</sub> = 15 A	-	1.03	1.25	V	
Forward voltage, per diode	V <sub>F</sub>	٧F	I <sub>F</sub> = 15 A, T <sub>J</sub> = 150 °C	-	0.9	1.1	
De construir de la construir d		V <sub>R</sub> = V <sub>R</sub> rated	-	-	15		
Reverse leakage current, per diode I <sub>R</sub>		T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	70	300	- μA	
Junction capacitance, per diode	C <sub>T</sub>	V <sub>R</sub> = 600 V	-	13	-	pF	



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 A, dI_F/dt = 50 A$	$I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		55	1	
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1 A, I <sub>rr</sub> = 0.25 A		-	-	65	]
Reverse recovery time		T <sub>J</sub> = 25 °C	I <sub>F</sub> = 15 A, dI <sub>F</sub> /dt = 500 A/μs, V <sub>R</sub> = 400 V	-	96	-	ns
		T <sub>J</sub> = 125 °C		-	150	-	
Dook receives augreent	1	T <sub>J</sub> = 25 °C		-	18	-	Α
Peak recovery current I <sub>F</sub>	I <sub>RRM</sub>	T <sub>J</sub> = 125 °C		-	26	-	_ ^
Payaraa raaayany aharaa	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	1.0	1	μC
Reverse recovery charge		T <sub>J</sub> = 125 °C		-	2.0	-	μΟ

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55	-	+175	°C
Thermal resistance, per diode junction to solder pad	R <sub>thJ-Sp</sub>		=	1.2	1.7	°C/W
Approximate weight				0.55		g
Approximate weight				0.02		oz.
Marking device		Case style SMPD (TO-263AC)		30C	DU06	-

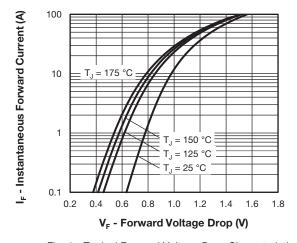


Fig. 1 - Typical Forward Voltage Drop Characteristics

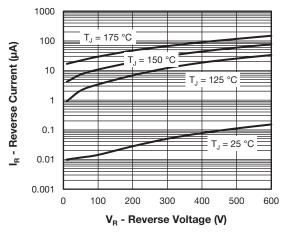


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

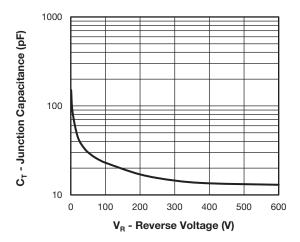


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

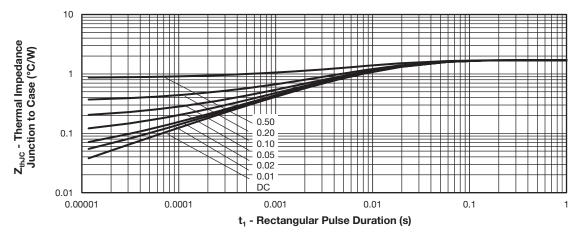


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

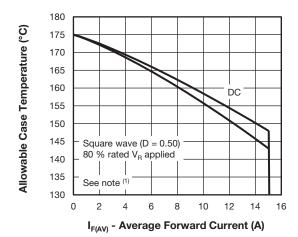


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

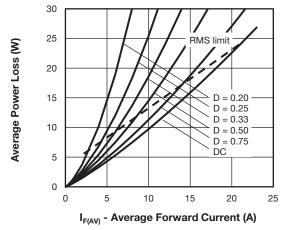


Fig. 6 - Forward Power Loss Characteristics

#### Note

<sup>(1)</sup> Formula used:  $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$ ;  $Pd = forward power loss = I_{F(AV)} \times V_{FM} at (I_{F(AV)}/D)$  (see fig. 5);  $Pd_{REV} = inverse power loss = V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = rated V_R$ 



#### www.vishay.com

## Vishay Semiconductors

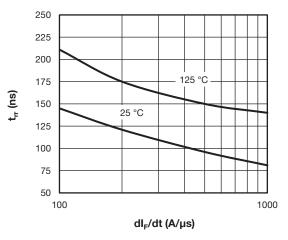


Fig. 7 - Typical Reverse Recovery Time vs. dI<sub>F</sub>/dt

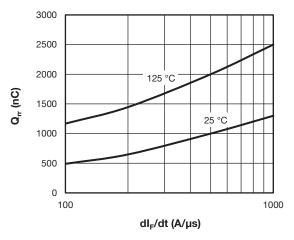
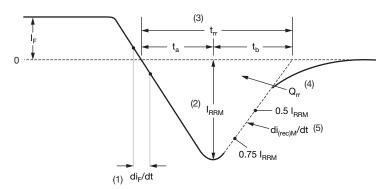


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{RRM}$  peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm l_{r}$  to point where a line passing through 0.75  $\rm l_{RRM}$  and 0.50  $\rm l_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{\rm rr}$  area under curve defined by  $\mathbf{t}_{\rm rr}$  and  $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

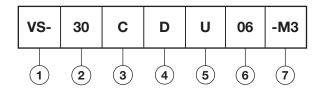
(5) di<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 9 - Reverse Recovery Waveform and Definitions



#### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

Current rating (30 A)

3 - Circuit configuration:

C = common cathode

- D = SMPD package

5 - Process type,

U = ultrafast recovery

6 - Voltage code (06 = 600 V)

7 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

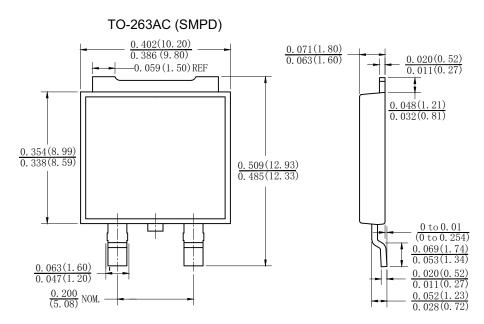
ORDERING INFORMATION (Example)					
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION		
VS-30CDU06-M3/I	2000	2000	13" diameter plastic tape and reel		

LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95604</u>				
Part marking information	www.vishay.com/doc?95566			
Packaging information	www.vishay.com/doc?88869			
SPICE model	www.vishay.com/doc?96576			

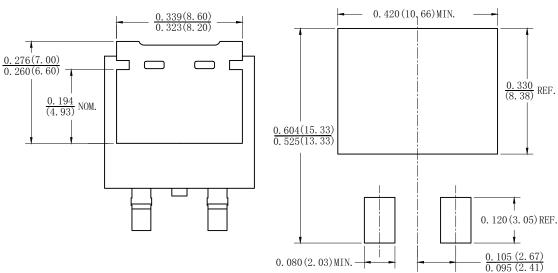


# TO-263AC (SMPD)

### **DIMENSIONS** in inches (millimeters)



### Mounting Pad Layout





### **Legal Disclaimer Notice**

Vishay

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